

JC12 Rec'd PCT/PTC 27 SEP 2005

| | | |
|---|--|--------------------|
| <p>INFORMATION DISCLOSURE STATEMENT</p> <p>PTO-1449</p> | <p>Atty. Docket No. ABE-034</p> | <p>10/55076</p> |
| | <p>Applicant: Eiji KAMIYAMA et al.</p> | |
| | <p>Filing Date: September 27, 2005</p> | <p>Group: 1763</p> |

U.S. PATENT DOCUMENTS

| Examiner's Initial | | Document No. | Date | Name | Class | Sub Class | Filing Date If appropriate |
|--------------------|----|--------------|----------|--------------|-------|-----------|----------------------------|
| /RC/ | UA | 5,882,987 A | 03/16/99 | Srikrishnan | 438 | 458 | |
| /RC/ | UB | 6,140,210 A | 10/31/00 | Aga et al. | 438 | 458 | |
| /RC/ | UC | 6,372,609 B1 | 04/16/02 | Aga et al. | 438 | 459 | |
| /RC/ | UD | 5,374,564 A | 12/20/94 | Bruehl | 437 | 24 | |
| /RC/ | UE | 6,020,252 A | 02/01/00 | Aspar et al. | 438 | 458 | |
| | UF | | | | | | |
| | UG | | | | | | |

FOREIGN PATENT DOCUMENTS

| Examiner's Initial | | Document No. | Date | Country | Translation Yes/No/Partial |
|--------------------|----|---------------|----------|---------|----------------------------|
| /RC/ | FA | 11-121377 A | 04/30/99 | JP | Abstract |
| /RC/ | FB | 11-102848 A | 04/13/99 | JP | Abstract |
| /RC/ | FC | 2000-124092 A | 04/28/00 | JP | Abstract |
| /RC/ | FD | 2003-17723 A | 01/17/03 | JP | Abstract & Translation |
| /RC/ | FE | 2004-80035 A | 03/11/04 | JP | Abstract & Translation |
| | FF | | | | |

OTHER DOCUMENTS

| Examiner's Initial | | |
|--------------------|----|--|
| /RC/ | DA | Auberton-Hervé, A.J. et al., "SMART-CUT®: The Basic Fabrication Process for UNIBOND® SOI Wafers," <i>IEICE TRANS ELECTRON</i> , Vol. E80 C, No. 3, 1997, pp. 358-363. |
| /RC/ | DB | Tong, Q. Y. et al., "SemiConductor Wafer Bonding: Science and Technology"; November, 1998; printout of website http://www3.interscience.wiley.com:8100/WileyCDA/WileyTitle/productCd-0471574813_descCd-description.html?print=true . |
| | DC | |

| | |
|------------------------------------|------------------------------------|
| <p>Examiner: /Roberts Culbert/</p> | <p>Date Considered: 08/05/2007</p> |
|------------------------------------|------------------------------------|

KTK/jbf

| | | |
|---|------------------------------------|----------------------------|
| INFORMATION DISCLOSURE STATEMENT PTO-1449 | Atty. Docket No. ABE-034 | Serial No. Not assigned |
| | Applicant: Eiji KAMIYAMA et al. | |
| | Filing Date: September 27, 2005 | Group: Not assigned |

U.S. PATENT DOCUMENTS

| Examiner's Initial | | Document No. | Date | Name | Class | Sub Class | Filing Date If appropriate |
|--------------------|----|--------------|----------|--------------|-------|-----------|----------------------------|
| /RC/ | UA | 5,882,987 A | 03/16/99 | Srikrishnan | 438 | 458 | |
| /RC/ | UB | 6,140,210 A | 10/31/00 | Aga et al. | 438 | 458 | |
| /RC/ | UC | 6,372,609 B1 | 04/16/02 | Aga et al. | 438 | 459 | |
| /RC/ | UD | 5,374,564 A | 12/20/94 | Bruel | 437 | 24 | |
| /RC/ | UE | 6,020,252 A | 02/01/00 | Aspar et al. | 438 | 458 | |
| | UF | | | | | | |
| | UG | | | | | | |

FOREIGN PATENT DOCUMENTS

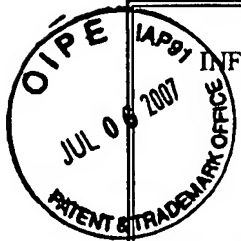
| Examiner's Initial | | Document No. | Date | Country | Translation Yes/No/Partial |
|--------------------|----|---------------|----------|---------|----------------------------|
| /RC/ | FA | 11-121377 A | 04/30/99 | JP | Abstract |
| /RC/ | FB | 11-102848 A | 04/13/99 | JP | Abstract |
| /RC/ | FC | 2000-124092 A | 04/28/00 | JP | Abstract |
| /RC/ | FD | 2003-17723 A | 01/17/03 | JP | Abstract & Translation |
| /RC/ | FE | 2004-80035 A | 03/11/04 | JP | Abstract & Translation |
| | FF | | | | |

OTHER DOCUMENTS

| Examiner's Initial | | |
|--------------------|----|--|
| /RC/ | DA | Auberton-Hervé, A.J. et al., "SMART-CUT®: The Basic Fabrication Process for UNIBOND® SOI Wafers," <i>IEICE TRANS ELECTRON</i> , Vol. E80 C, No. 3, 1997, pp. 358-363. |
| /RC/ | DB | Tong, Q.Y. et al., "SemiConductor Wafer Bonding: Science and Technology"; November, 1998; printout of website http://www3.interscience.wiley.com:8100/WileyCDA/WileyTitle/productCd-0471574813_descCd-description.html?print=true . |
| | DC | |

| | |
|-----------------------------|-----------------------------|
| Examiner: /Roberts Culbert/ | Date Considered: 08/05/2007 |
|-----------------------------|-----------------------------|

KTK/jbf



| | | | |
|--|--|------------------------------------|--------------------------------|
| INFORMATION DISCLOSURE STATEMENT PTO-1449 | | Atty. Docket No. ABE-034 | Serial No. 10/550,761 |
| | | Applicant: Eiji KAMIYAMA et al. | |
| | | Filing Date: January 9, 2006 | Group: 2012 1763 |

U.S. PATENT DOCUMENTS

| Examiner's Initial | | Document No. | Date | Name | Class | Sub Class | Filing Date If appropriate |
|--------------------|----|--------------|----------|------------|-------|-----------|----------------------------|
| /RC/ | UA | 6,323,108 B1 | 11/27/01 | Kub et al. | 438 | 458 | |
| | UB | | | | | | |
| | UC | | | | | | |
| | UD | | | | | | |
| | UE | | | | | | |
| | UF | | | | | | |
| | UG | | | | | | |

FOREIGN PATENT DOCUMENTS

| Examiner's Initial | | Document No. | Date | Country | Translation Yes/No/Partial |
|--------------------|----|--------------|----------|---------|----------------------------|
| /RC/ | FA | 1 045 448 A1 | 10/18/00 | EP | |
| /RC/ | FB | 0 905 767 A1 | 03/31/99 | EP | |
| /RC/ | FC | 1 085 562 A2 | 03/21/01 | EP | |
| | FD | | | | |
| | FE | | | | |
| | FF | | | | |
| | FG | | | | |

OTHER DOCUMENTS

| Examiner's Initial | | |
|--------------------|----|--|
| | DA | |
| | DB | |
| | DC | |

| | |
|-----------------------------|-----------------------------|
| Examiner: /Roberts Culbert/ | Date Considered: 08/05/2007 |
|-----------------------------|-----------------------------|

KTK/trb/tms